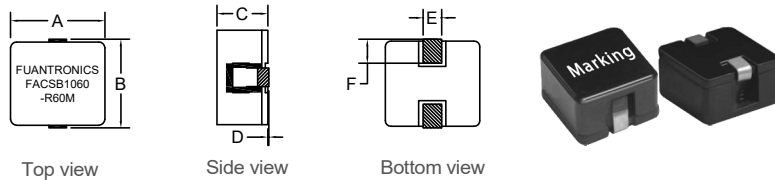


P/N: FACSB1060-R60M

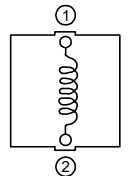


Outline Dimensions(Unit:mm)

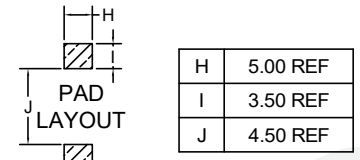


A	B	C	D	E	F
±0.50	±1.00	±0.30		±0.50	±1.00
10.2	10.5	5.70	0-0.2	2.00	2.50

Electronical Schematic



Suggested Pad layout



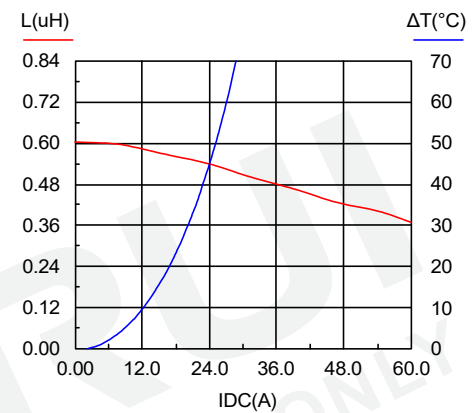
- \*\*\*Magnetic shielded structure: excellent resistance to electro magnetic interferenc(EMI).
- \*\*\*Flat wire winding, achieve a low D.C. Resistance.
- \*\*\*Low loss, high efficiency, wide application frequency and application scope.
- \*\*\*Lightweight design, save space, suitable for high density SMT.

Electrical Characteristics(@25°C)

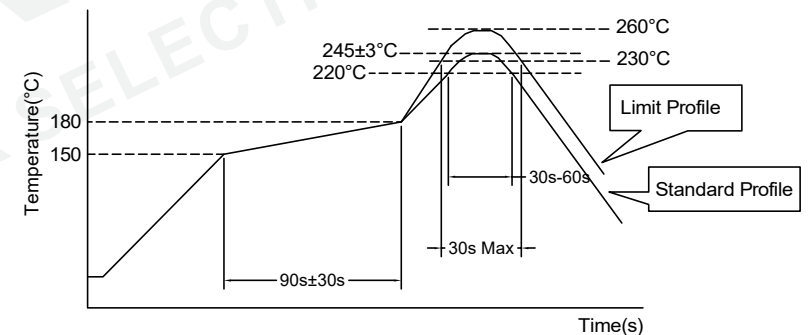
Inductance 100KHz,0.1V	DC Resistor	Saturated current 45A	Temperature rise current 25A
0.60uH±20%	1.10mΩ Max	L(45A)=70%*L0A Typ	T≤50°C Typ

- \*\*\*Saturation current: the actual value of DC current when the inductance decrease 30% of its initial value.
- \*\*\*Temperature rise current: the actual value of DC current when the temperature rise is ΔT50°C(Ta=25°C).
- \*\*\*Operating Temperature: -40°C~+125°C. (Temperature rise included)
- \*\*\*Storage Temperature: -40°C~+125°C.
- \*\*\*Storage Humidity:RH10%~70%.

Saturation current VS temperature rise current curve:



Recommended Soldering Temperature Graph.



	Standard Profile	Standard Profile
Pre-heating	150~180°C,90s±30s	
Heating	above 220°C,30s-60s	above 240°C,30s Max
Peak temperature	245°C±3°C	260°C,10s
Cycle of reflow	2 times	